

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

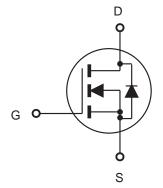
■ 30V, 100A, $R_{DS(ON)} = 5.3m\Omega$ @ $V_{GS} = 10V$.

$$R_{DS(ON)} = 8.0 m \Omega \quad @V_{GS} = 4.5 V.$$

- \blacksquare Super high dense cell design for extremely low R_{DS(ON)}.
- High power and current handing capability.
- Lead free product is acquired.
- TO-220 & TO-263 package.







ABSOLUTE MAXIMUM RATINGS $T_c = 25^{\circ}C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	100	А
Drain Current-Pulsed ^a	I _{DM}	400	А
Maximum Power Dissipation @ T _C = 25°C	В	100	W
- Derate above 25°C	P _D	0.67	W/°C
Single Pulsed Avalanche Energy d	E _{AS}	875	mJ
Single Pulsed Avalanche Current d	I _{AS}	35	А
Operating and Store Temperature Range	T_J, T_stg	-55 to 175	°C

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	Reuc	1.5	°C/W
Thermal Resistance, Junction-to-Ambient	RеJA	62.5	°C/W

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Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Тур	Max	Units			
Off Characteristics									
Drain-Source Breakdown Voltage	BV _{DSS}	$V_{GS} = 0V, I_{D} = 250\mu A$	30			V			
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30V, V_{GS} = 0V$			1	μA			
Gate Body Leakage Current, Forward	I _{GSSF}	$V_{GS} = 20V, V_{DS} = 0V$			100	nA			
Gate Body Leakage Current, Reverse	Igssr	$V_{GS} = -20V, V_{DS} = 0V$			-100	nA			
On Characteristics ^b									
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1		3	V			
Static Drain-Source	D	$V_{CS} = 10V$. $I_D = 50A$		4.2	5.3	mΩ			
On-Resistance	R _{DS(on)}	$V_{GS} = 4.5V, I_{D} = 40A$		6.0	8.0	mΩ			
Forward Transconductance	9 _{FS}	$V_{DS} = 10V, I_{D} = 15A$		27		S			
Dynamic Characteristics °									
Input Capacitance	C _{iss}	\/ 45\/\\ 0\/		9500		pF			
Output Capacitance	C _{oss}	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1.0 MHz		800		pF			
Reverse Transfer Capacitance	C _{rss}]		300		pF			
Switching Characteristics °									
Turn-On Delay Time	t _{d(on)}	V _{DD} = 15V, I _D = 1A,		25.7	50	ns			
Turn-On Rise Time	t _r			10	20	ns			
Turn-Off Delay Time	t _{d(off)}	$V_{GS} = 10V, R_{GEN} = 6\Omega$		128	200	ns			
Turn-Off Fall Time	t _f			34	70	ns			
Total Gate Charge	Qg	\/ 45\/ 400		50	65	nC			
Gate-Source Charge	Q _{gs}	$V_{DS} = 15V, I_{D} = 16A, V_{GS} = 5V$		20.8		nC			
Gate-Drain Charge	Q_{gd}	7 .62 - 01		19		nC			
Drain-Source Diode Characteristics and Maximun Ratings									
Drain-Source Diode Forward Current	I _S				90	Α			
Drain-Source Diode Forward Voltage b	V _{SD}	$V_{GS} = 0V, I_{S} = 20A$			1.5	V			

Notes : a. Repetitive Rating : Pulse width limited by maximum junction temperature b.Pulse Test : Pulse Width \leq 300µs, Duty Cycle \leq 2%. c.Guaranteed by design, not subject to production testing. d.L = 0.5mH, I_{AS} = 35A, V_{DD} = 25V, R_G = 25 Ω , Starting T_J = 25°C



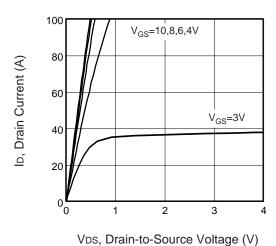


Figure 1. Output Characteristics

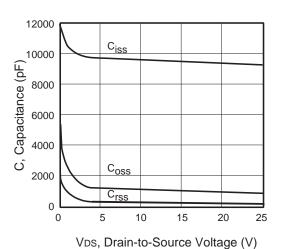


Figure 3. Capacitance

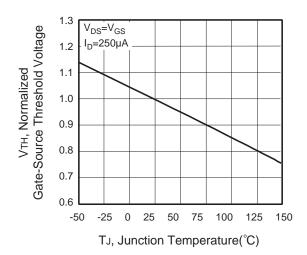


Figure 5. Gate Threshold Variation with Temperature

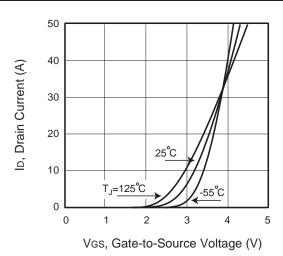


Figure 2. Transfer Characteristics

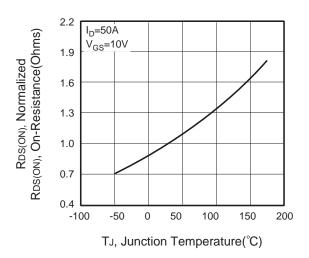


Figure 4. On-Resistance Variation with Temperature

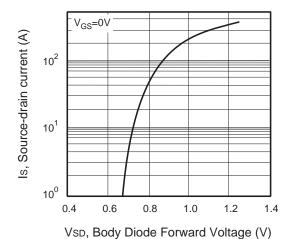


Figure 6. Body Diode Forward Voltage Variation with Source Current



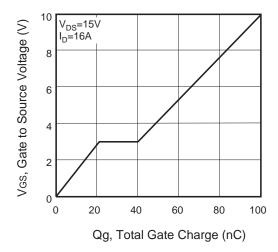


Figure 7. Gate Charge

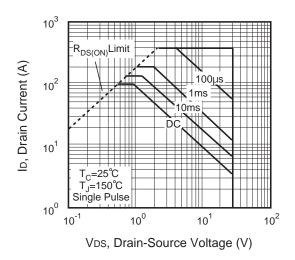


Figure 8. Maximum Safe Operating Area

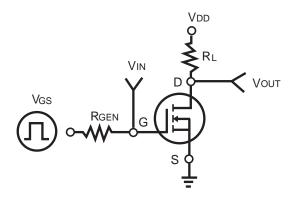


Figure 9. Switching Test Circuit

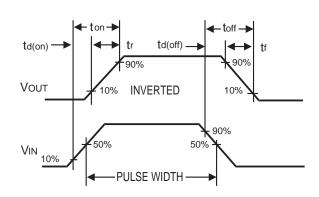


Figure 10. Switching Waveforms

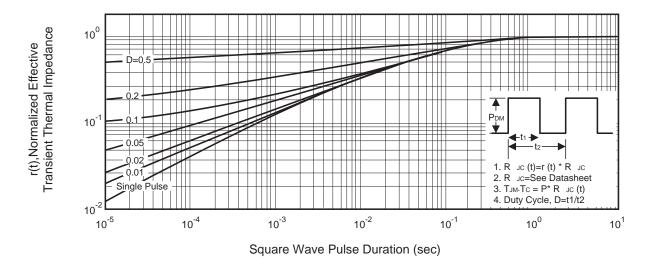


Figure 11. Normalized Thermal Transient Impedance Curve